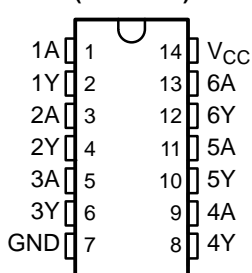


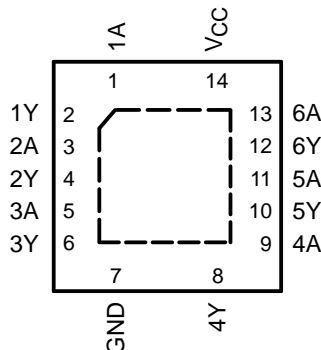
## FEATURES

- Operate From 1.65 V to 3.6 V
- Specified From  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ ,  $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ , and  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$
- Inputs and Open-Drain Outputs Accept Voltages up to 5.5 V
- Max  $t_{pd}$  of 3.7 ns at 3.3 V
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17

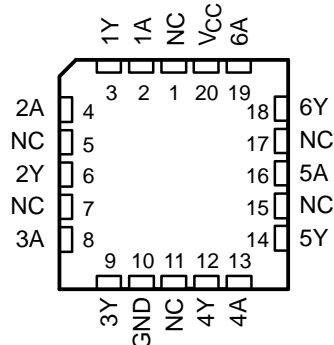
SN54LVC06A . . . J OR W PACKAGE  
SN74LVC06A . . . D, DB, DGV, NS,  
OR PW PACKAGE  
(TOP VIEW)



SN74LVC06A . . . RGY PACKAGE  
(TOP VIEW)



SN54LVC06A . . . FK PACKAGE  
(TOP VIEW)



NC - No internal connection

## DESCRIPTION/ORDERING INFORMATION

These hex inverter buffers/drivers are designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The outputs of the 'LVC06A devices are open drain and can be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions. The maximum sink current is 24 mA.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
$-40^{\circ}\text{C}$ to $85^{\circ}\text{C}$	QFN – RGY	Reel of 1000	SN74LVC06ARGYR	LC06A
$-40^{\circ}\text{C}$ to $125^{\circ}\text{C}$	SOIC – D	Tube of 50	SN74LVC06AD	LVC06A
		Reel of 2500	SN74LVC06ADR	
		Reel of 250	SN74LVC06ADT	
	SOP – NS	Reel of 2000	SN74LVC06ANSR	LVC06A
	SSOP – DB	Reel of 2000	SN74LVC06ADBR	LC06A
	TSSOP – PW	Tube of 90	SN74LVC06APW	LC06A
		Reel of 2000	SN74LVC06APWR	
		Reel of 250	SN74LVC06APWT	
$-55^{\circ}\text{C}$ to $125^{\circ}\text{C}$	TVSOP – DGV	Reel of 2000	SN74LVC06ADGVR	LC06A
	CDIP – J	Tube of 25	SNJ54LVC06AJ	SNJ54LVC06AJ
	CFP – W	Tube of 150	SNJ54LVC06AW	SNJ54LVC06AW
	LCCC – FK	Tube of 55	SNJ54LVC06AFK	SNJ54LVC06AFK

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

# SN54LVC06A, SN74LVC06A

## HEX INVERTER BUFFERS/DRIVERS

### WITH OPEN-DRAIN OUTPUTS

SCAS596N–OCTOBER 1997–REVISED JULY 2005

## DESCRIPTION/ORDERING INFORMATION (CONTINUED)

These devices are fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

**FUNCTION TABLE**  
**(EACH INVERTER)**

INPUT A	OUTPUT Y
H	L
L	H

**LOGIC DIAGRAM, EACH INVERTER (POSITIVE LOGIC)**



## Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	–0.5	6.5	V
$V_I$	Input voltage range <sup>(2)</sup>	–0.5	6.5	V
$V_O$	Output voltage range	–0.5	6.5	V
$I_{IK}$	Input clamp current		–50	mA
$I_{OK}$	Output clamp current		–50	mA
$I_O$	Continuous output current		±50	mA
	Continuous current through $V_{CC}$ or GND		±100	mA
$\theta_{JA}$	Package thermal impedance	D package <sup>(3)</sup>	86	°C/W
		DB package <sup>(3)</sup>	96	
		DGV package <sup>(3)</sup>	127	
		NS package <sup>(3)</sup>	76	
		PW package <sup>(3)</sup>	113	
		RGY package <sup>(4)</sup>	47	
$T_{stg}$	Storage temperature range	–65	150	°C
$P_{tot}$	Power dissipation <sup>(5)(6)</sup>	$T_A = -40^{\circ}\text{C to } 125^{\circ}\text{C}$		500 mW

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.
- (4) The package thermal impedance is calculated in accordance with JESD 51-5.
- (5) For the D package: above 70°C the value of  $P_{tot}$  derates linearly with 8 mW/K.
- (6) For the DB, DGV, NS, and PW packages: above 60°C the value of  $P_{tot}$  derates linearly with 5.5 mW/K.

## Recommended Operating Conditions<sup>(1)</sup>

			SN54LVC06A <sup>(2)</sup>		UNIT
			−55°C to 125°C		
			MIN	MAX	
V <sub>CC</sub>	Supply voltage	Operating	1.65	3.6	V
		Data retention only	1.5		
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		
		V <sub>CC</sub> = 2.7 V to 3.6 V	2		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.35 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.7		
		V <sub>CC</sub> = 2.7 V to 3.6 V	0.8		
V <sub>I</sub>	Input voltage		0	5.5	V
V <sub>O</sub>	Output voltage		0	5.5	V
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V	4		mA
		V <sub>CC</sub> = 2.3 V	8		
		V <sub>CC</sub> = 2.7 V	12		
		V <sub>CC</sub> = 3 V	24		

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

(2) Product preview

## Recommended Operating Conditions<sup>(1)</sup>

			SN74LVC06A						UNIT
			T <sub>A</sub> = 25°C		–40°C to 85°C		–40°C to 125°C		
			MIN	MAX	MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	Operating	1.65	3.6	1.65	3.6	1.65	3.6	V
		Data retention only	1.5		1.5		1.5		
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>		0.65 × V <sub>CC</sub>		0.65 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		1.7		1.7		
		V <sub>CC</sub> = 2.7 V to 3.6 V	2		2		2		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.35 × V <sub>CC</sub>		0.35 × V <sub>CC</sub>		0.35 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.7		0.7		0.7		
		V <sub>CC</sub> = 2.7 V to 3.6 V	0.8		0.8		0.8		
V <sub>I</sub>	Input voltage		0	5.5	0	5.5	0	5.5	V
V <sub>O</sub>	Output voltage		0	5.5	0	5.5	0	5.5	V
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V	4		4		4		mA
		V <sub>CC</sub> = 2.3 V	8		8		8		
		V <sub>CC</sub> = 2.7 V	12		12		12		
		V <sub>CC</sub> = 3 V	24		24		24		

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN54LVC06A, SN74LVC06A

## HEX INVERTER BUFFERS/DRIVERS

### WITH OPEN-DRAIN OUTPUTS

SCAS596N–OCTOBER 1997–REVISED JULY 2005

## Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	SN54LVC06A <sup>(1)</sup>		UNIT
			–55°C to 125°C		
			MIN	TYP <sup>(2)</sup> MAX	
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V	0.2		V
	I <sub>OL</sub> = 4 mA	1.65 V	0.45		
	I <sub>OL</sub> = 8 mA	2.3 V	0.7		
	I <sub>OL</sub> = 12 mA	2.7 V	0.4		
	I <sub>OL</sub> = 24 mA	3 V	0.55		
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	3.6 V	±5		μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V	10		μA
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V	500		μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	5		pF

(1) Product preview

(2)  $T_A = 25^\circ\text{C}$

## Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	SN74LVC06A						UNIT	
			T <sub>A</sub> = 25°C			−40°C to 85°C		−40°C to 125°C		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V	0.1			0.2		0.3		V
	I <sub>OL</sub> = 4 mA	1.65 V	0.24			0.45		0.6		
	I <sub>OL</sub> = 8 mA	2.3 V	0.3			0.7		0.75		
	I <sub>OL</sub> = 12 mA	2.7 V	0.4			0.4		0.6		
	I <sub>OL</sub> = 24 mA	3 V	0.55			0.55		0.8		
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	3.6 V	±1			±5		±20		μA
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0	±1			±10		±20		μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V	1			10		40		μA
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> − 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V	500			500		5000		μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	5							pF

## Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	SN54LVC06A <sup>(1)</sup>		UNIT
				–55°C to 125°C		
				MIN	MAX	
t <sub>pd</sub>	A	Y	1.8 V ± 0.15 V	1.4	5.6	ns
			2.5 V ± 0.2 V	1	3.1	
			2.7 V		3.9	
			3.3 V ± 0.3 V	1	3.7	

(1) Product preview

## Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

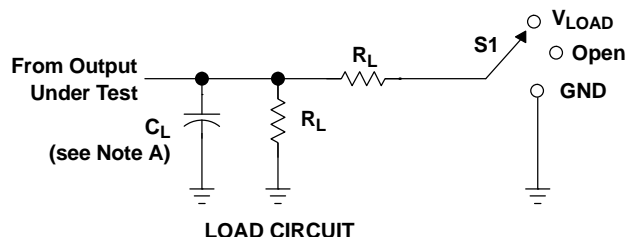
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	SN74LVC06A						UNIT	
				T <sub>A</sub> = 25°C			−40°C to 85°C		−40°C to 125°C		
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A	Y	1.8 V ± 0.15 V	1.4	3	5.1	1.4	5.6	1.4	7.6	ns
			2.5 V ± 0.2 V	1	1.9	2.8	1	3.1	1	4	
			2.7 V	1	2.4	3.7	1	3.9	1	5	
			3.3 V ± 0.3 V	1	2.2	3.5	1	3.7	1	5	

## Operating Characteristics

T<sub>A</sub> = 25°C

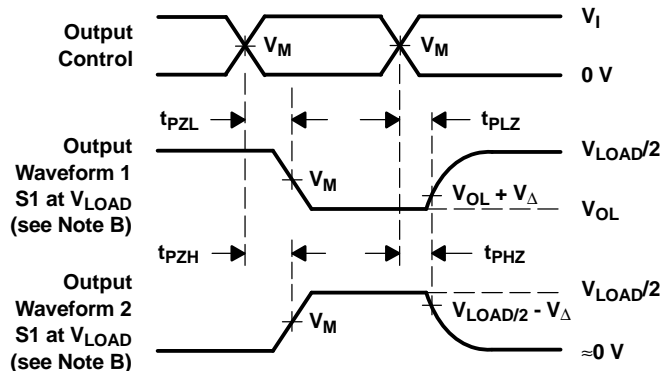
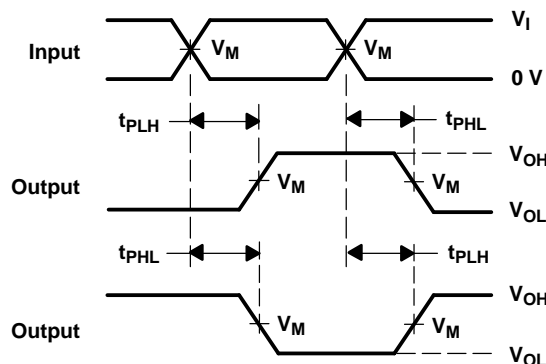
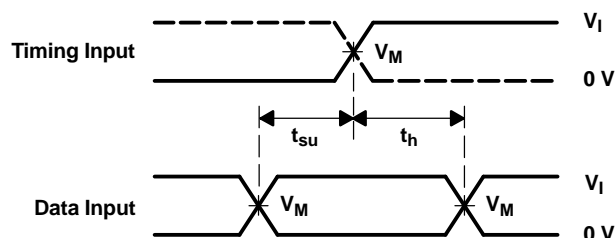
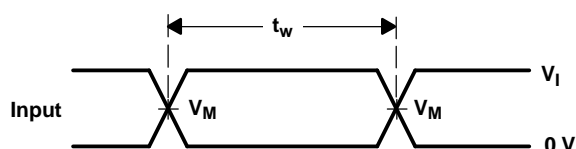
PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per buffer/driver	f = 10 MHz	1.8 V	2.1	pF
			2.5 V	2.3	
			3.3 V	2.5	

## PARAMETER MEASUREMENT INFORMATION (OPEN DRAIN)



TEST	S1
$t_{PZL}$ (see Notes E and F)	$V_{LOAD}$
$t_{PLZ}$ (see Notes E and G)	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	$V_{LOAD}$

$V_{CC}$	INPUT		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ .
  - The outputs are measured one at a time, with one transition per measurement.
  - Since this device has open-drain outputs,  $t_{PLZ}$  and  $t_{PZL}$  are the same as  $t_{pd}$ .
  - $t_{PZL}$  is measured at  $V_M$ .
  - $t_{PLZ}$  is measured at  $V_{OL} + V_{\Delta}$ .
  - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LVC06AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADGVRE4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74LVC06APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ARGYR	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

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a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

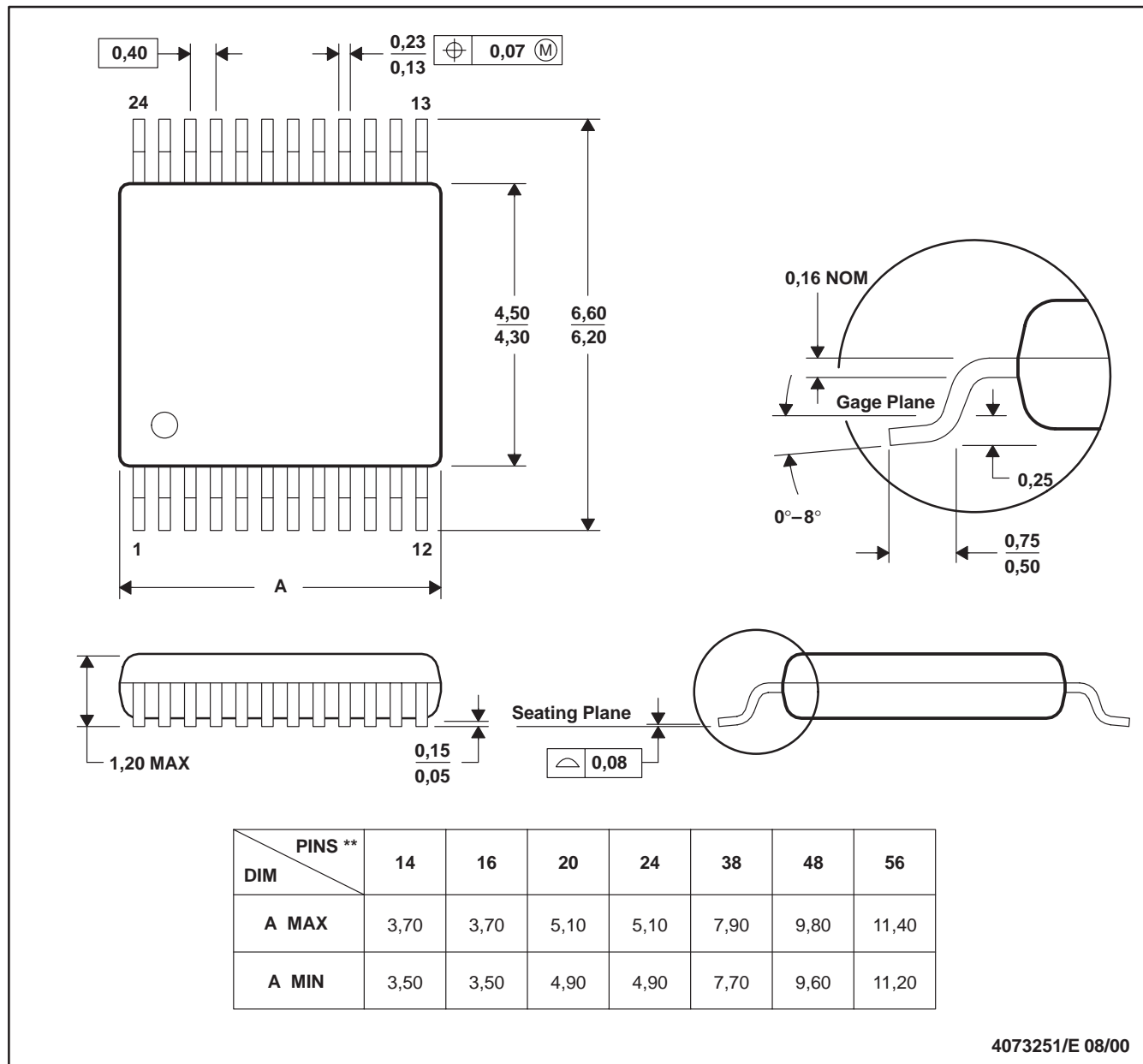
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## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

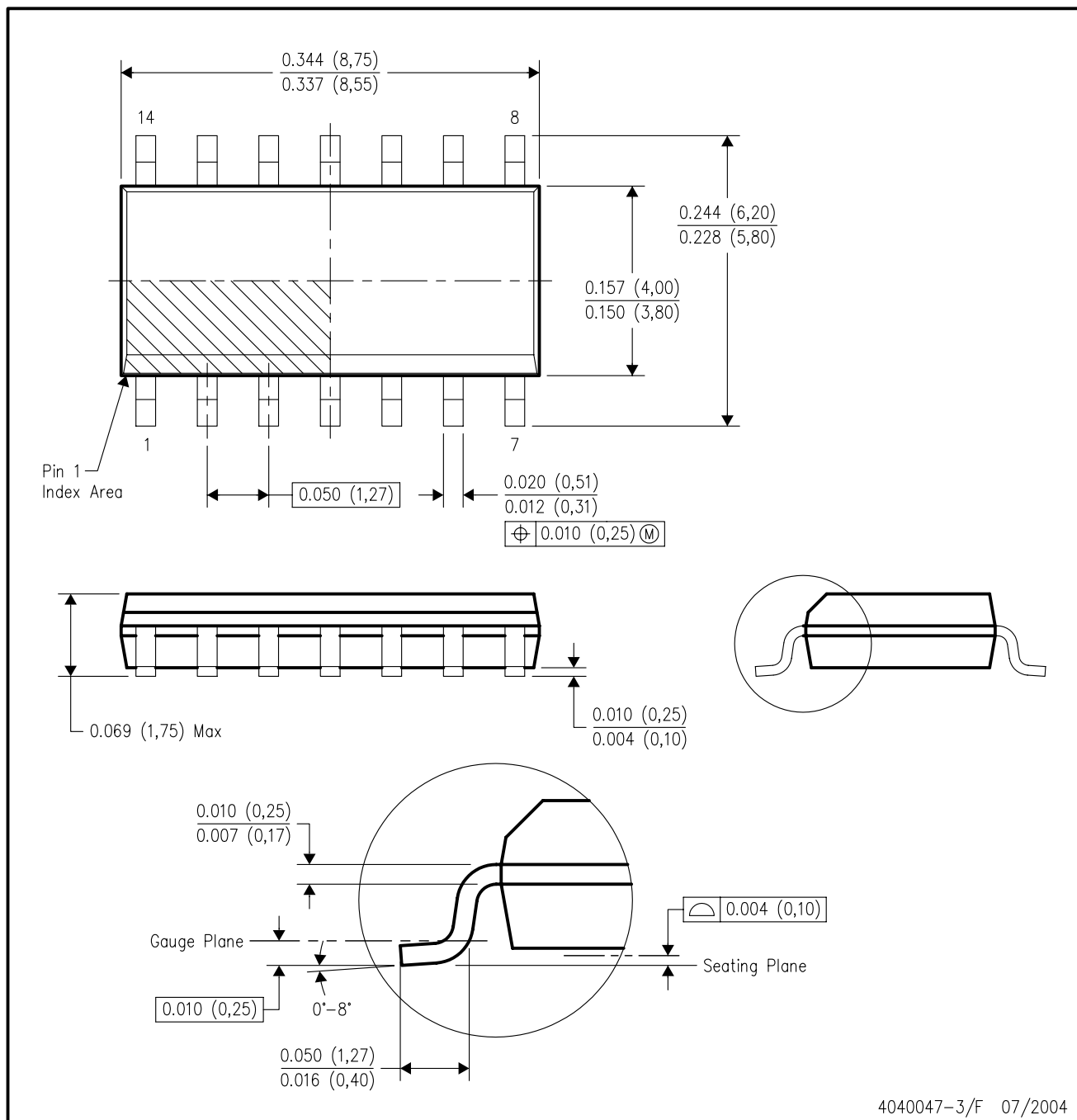
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

## D (R-PDSO-G14)

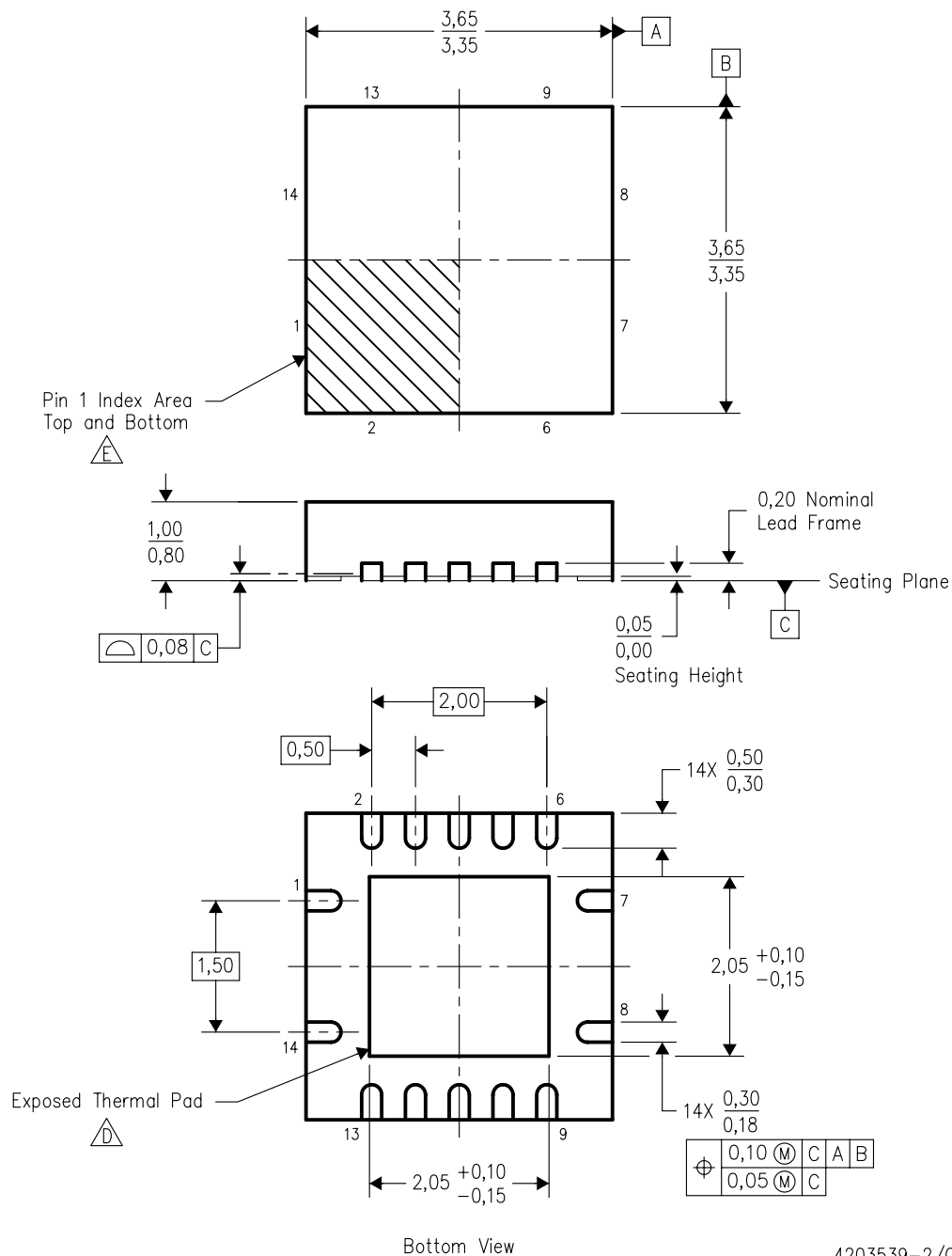
## PLASTIC SMALL-OUTLINE PACKAGE





4040047-3/F 07/2004

RGY (S-PQFP-N14)

## PLASTIC QUAD FLATPACK



4203539-2/G 04/2005

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. QFN (Quad Flatpack No-Lead) package configuration.
  -  D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
  -  E. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated.  
The Pin 1 identifiers are either a molded, marked, or metal feature.
  - F. Package complies to JEDEC MO-241 variation BA.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

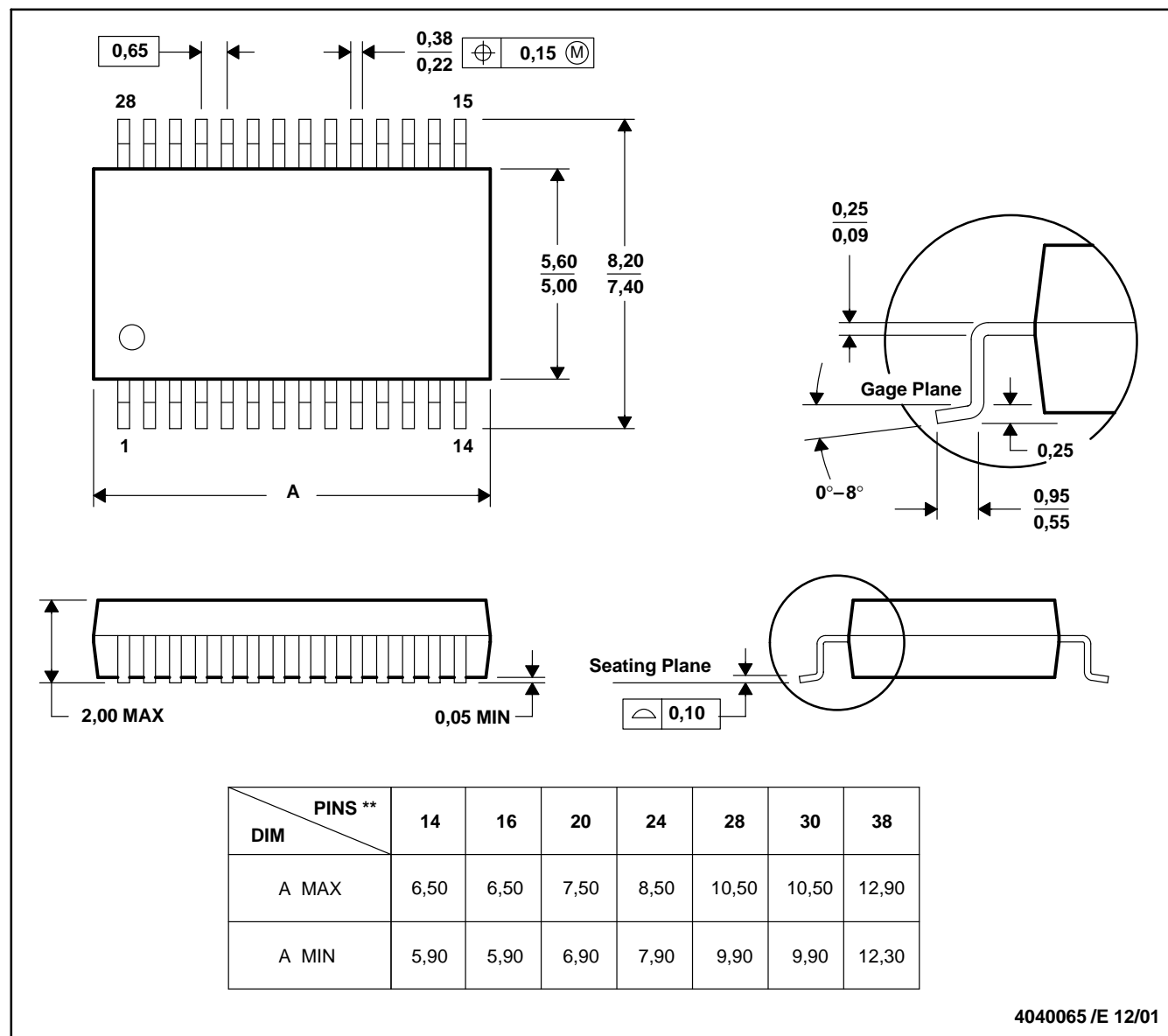
4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN

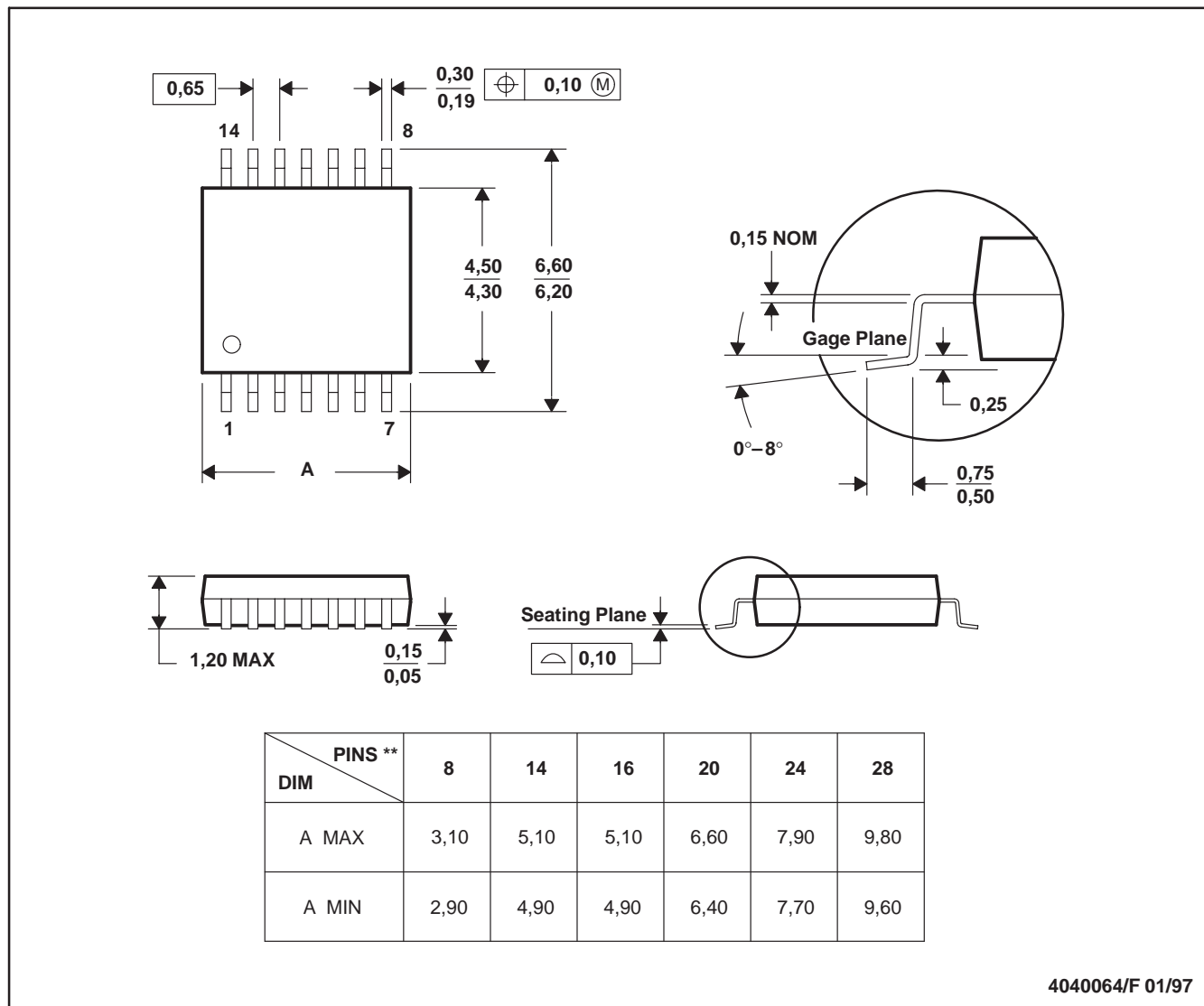


- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

## PW (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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